

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	802	29/603.07-603.17.ccls. and (magnetic adj head)	USPAT; JPO; DERWENT	OR	ON	2004/08/12 12:08
S3	2	("6174736").PN.	USPAT; USOCR; JPO; DERWENT	OR	OFF	2004/08/12 11:10
S4	388	wafer and (magnetic adj head) and bar and cut\$4	USPAT; JPO; DERWENT	OR	ON	2004/08/12 11:11
S5	259	(wafer and (magnetic adj head) and bar and cut\$4) and (polish\$3 or lap\$4)	USPAT; JPO; DERWENT	OR	ON	2004/08/12 11:12
S6	16	((wafer and (magnetic adj head) and bar and cut\$4) and (polish\$3 or lap\$4)) and base and underly\$3	USPAT; JPO; DERWENT	OR	ON	2004/08/12 12:07
S8	542	29/603.07-603.17.ccls. and (magnetic adj head) and (polish\$3 or lap\$4)	USPAT; JPO; DERWENT	OR	ON	2004/08/12 12:08
S10	128	451/5,41.ccls. and (magnetic adj head) and (polish\$3 or lap\$4)	USPAT; JPO; DERWENT	OR	ON	2004/08/12 12:09
S11	6	216/65.ccls. and (magnetic adj head) and (polish\$3 or lap\$4)	USPAT; JPO; DERWENT	OR	ON	2004/08/12 12:25
S12	19	(wafer and (magnetic adj head) and bar and cut\$4) and (360/122, 313.ccls. and (magnetic adj head) and (polish\$3 or lap\$4))	USPAT; JPO; DERWENT	OR	ON	2004/08/12 12:25
S13	1	"5726841".PN.	USPAT	OR	ON	2004/08/12 12:17
S14	8	("4797765" "5079831" "5116719" "5331497" "5508863" "5578342" "5580602" "5659451").PN.	USPAT	OR	ON	2004/08/12 12:20
S15	74	(wafer and (magnetic adj head) and bar and cut\$4) and (29/603.07-603.17.ccls. and (magnetic adj head) and (polish\$3 or lap\$4))	USPAT; JPO; DERWENT	OR	ON	2004/08/12 12:27
S16	44	(wafer and (magnetic adj head) and bar and cut\$4) and (451/5,41.ccls. and (magnetic adj head) and (polish\$3 or lap\$4))	USPAT; JPO; DERWENT	OR	ON	2005/09/07 09:50
S17	14	216/65.ccls. and (magnetic adj head) and (polish\$3 or lap\$4 or etch\$3)	USPAT; JPO; DERWENT	OR	ON	2004/08/12 12:36

S18	151142	etch\$3 with (base or substrate)	USPAT; JPO; DERWENT	OR	ON	2004/08/12 12:28
S19	1	((wafer and (magnetic adj head) and bar and cut\$4) and (451/5,41. ccls. and (magnetic adj head) and (polish\$3 or lap\$4))) and (etch\$3 with (base or substrate))	USPAT; JPO; DERWENT	OR	ON	2004/08/12 12:28
S20	13	((wafer and (magnetic adj head) and bar and cut\$4) and (29/603. 07-603.17.ccls. and (magnetic adj head) and (polish\$3 or lap\$4))) and (etch\$3 with (base or substrate))	USPAT; JPO; DERWENT	OR	ON	2004/08/12 12:29
S21	6	("5567331" "5617273" "5841608" "5897984" "6287475" "6405426").PN.	USPAT	OR	ON	2004/08/12 12:31
S22	2814	216/22,39,41,48.ccls.	USPAT; JPO; DERWENT	OR	ON	2004/08/12 12:36
S23	276	216/22,39,41,48.ccls. and (magnetic adj head) and (polish\$3 or lap\$4 or etch\$3)	USPAT; JPO; DERWENT	OR	ON	2004/08/12 13:28
S24	14	(wafer and (magnetic adj head) and bar and cut\$4) and (216/22,39, 41,48.ccls. and (magnetic adj head) and (polish\$3 or lap\$4 or etch\$3))	USPAT; JPO; DERWENT	OR	ON	2004/08/12 12:36
S25	2	("6050879" "6166879").PN.	USPAT	OR	ON	2004/08/12 12:39
S22 3	6	(US-5841608-\$ or US-5872684-\$ or US-6057991-\$ or US-6444132-\$ or US-6470565-\$).did. or (JP-06004830-\$).did.	USPAT; JPO	OR	ON	2006/01/23 11:09
S22 4	0	(wafer and (magnetic adj head) and bar and cut\$4) and (451/5,41. ccls. and (magnetic adj head) and (polish\$3 or lap\$4))	EPO; JPO	OR	ON	2005/09/07 09:50
S22 5	21	(wafer and (magnetic adj head) and bar and cut\$4) and (magnetic adj head) and (polish\$3 or lap\$4)	EPO; JPO	OR	ON	2005/09/07 09:51
S22 6	0	S225 and @ad<10/10/2001	EPO; JPO	OR	ON	2005/09/07 09:51
S22 7	19	S225 and @ad<"20011010"	EPO; JPO	OR	ON	2005/09/07 10:43
S22 8	2	("6441715").PN.	USPAT; USOCR; JPO; DERWENT	OR	OFF	2005/09/08 09:04
S22 9	2	("6002553").PN.	USPAT; USOCR; JPO; DERWENT	OR	OFF	2005/09/08 09:04

S23 0	2	("6529346").PN.	US-PGPUB; USPAT; USOCR; JPO; DERWENT	OR	OFF	2006/01/23 10:56
S23 1	1515	(slider near section)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/23 11:13
S23 2	14088	(element near section)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/23 11:13
S23 3	42	S231 and S232	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/23 10:56
S23 4	17	(slider near section) same (element near section)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/23 11:06
S23 5	17	("5083365" "5142768" "5270895" "5331494" "5351158" "5402295" "5430592" "5452166" "5455730" "5469312" "5508862" "5625512" "5634259" "5673156" "5768055" "5777815" "5822153").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/23 11:00
S23 6	19	("5898542").URPN.	USPAT	OR	ON	2006/01/23 11:04
S23 7	8	(bond\$3 or attach\$3) same (slider near section) same (element near section)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/23 11:07
S23 8	48	wafer with (element near section)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/23 11:07
S23 9	42	wafer with (slider near section)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/23 11:07
S24 0	5	S238 and S239	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/23 11:07
S24 1	778	Sasaki-Yoshitaka.in. or Kamigama-Takehiro Kamigama.in.	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/23 11:10

S24 2	716	Sasaki-Yoshitaka.in. or Kamigama-Takehiro.in.	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/23 11:11
S24 3	14	S233 and S242	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/23 11:11
S24 4	6	(slider near section) near wafer	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/23 11:13
S24 5	4	(element near section) near wafer	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/23 11:14
S24 6	0	S244 and S245	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/23 11:14
S24 7	9	(US-5841608-\$ or US-6470565-\$ or US-6057991-\$ or US-6529346-\$ or US-5898542-\$ or US-5768055-\$ or US-5634259-\$).did. or (JP-06004830-\$ or JP-07029120-\$). did.	USPAT; JPO	OR	ON	2006/01/23 11:17
S24 9	5	S247 and (mask same etch\$3)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/23 11:37
S25 0	6	((("6934124") or ("6882505") or ("6529346"))).PN.	US-PGPUB; USPAT; USOCR; JPO; DERWENT	OR	OFF	2006/01/23 11:53
S25 1	11	(slider near body) same (head near element) same (bond\$3 or attach\$3)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/23 12:01
S25 2	4	("4130847" "5105529" "5768055" "5898542").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/01/23 11:59
S25 3	4	S250 and (bond\$3 or attach\$3)	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/23 12:01
S25 4	531	360/235.1,235.3,235.7,235.8,236.1, 236.3,246.2.ccls.	US-PGPUB; USPAT; JPO; DERWENT	OR	ON	2006/01/23 14:01



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» Key

IEEE JNL IEEE Journal or Magazine

IEE JNL IEE Journal or Magazine

IEEE CNF IEEE Conference Proceeding

IEE CNF IEE Conference Proceeding

IEEE STD IEEE Standard

- ☐ 1. Floating thin film head fabricated by ion etching method
Nakanishi, T.; Kogure, K.; Toshima, T.; Yanagisawa, K.;
Magnetics, IEEE Transactions on
Volume 16, Issue 5, Sep 1980 Page(s):785 - 787
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